VEER SURENDRA SAI UNIVERSITY OF TECHNOLOGY, BURLA DEPARTMENT OF METALLURGICAL AND MATERIALS ENGINEERING SESSION 2016 - 17 (ODD SEMESTER)

Total Pages-4

(Set-T,)

B.Tech - 7th(M & M) Surface Engineering

Full Marks: 70

Time: 3 hours

Answer six questions including Q. No. 1 which is compulsory

The figures in the right-hand margin indicate marks Symbols carry usual meaning

1. Answer all questions: 2×10

- (a) Why iron and chromium cannot be deposited as an alloy under normal conditions?
- (b) What is the scope of surface engineering in ceramics and polymers?
- (c) What is the difference between Carbonitriding and Nitro-carburising?

(Turn Over)

- (d) Write down the CVD ractions for the deposition of Si and SiO.
- (e) In between the APCVD and LPCVD process, which one is mass transfer controlled and which one is reaction rate controlled and why?
- Briefly explain surface treatment of a metal by Ion Implantation.
- (g) What are the advantages of Cu deposited by electrochemical method compared to Cu deposited by other methods?
- (h) Write down the advantages of cold wall reactor over hot wall reactor in a CVD process.
- (i) For deposition of TiN by sputter coating method from a Ti target material which gas should be used as a plasma generating gas and why?
- (i) If an aircraft flies through a dust cloud which type of wear process generally occurs and

how can you improve the wear resistance of the affected part.

2. (What is surface fatigue? Write down the	e
	different forms of a surface fatigue wear	r
	process.	

- (b) Describe the fretting wear process and write down the factors which affect the fretting wear process.
- (a) Explain the different possible wear mechanisms if a material is failed due to low adhesive wear resistance.
 - (b) In a slurry pipeline which type of wear process generally occur? Briefly describe the slurry erosion process.
- (a) Differentiate between the cathodic and 4. anodic inhibitors used to prevent a material from failing due to low corrosion resistance.
 - (b) What are absorption inhibitors and vapor phase inhibitors?

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5.	(a) Determine the growth rate of a CVD film and also discuss the two limiting cases which affect the growth rate.	5
	(b) State the different PVD processes and discuss the sputter coating technique.	5
6.	(a) With the help of a neat sketch explain the laser surface hardening method.	5
	(b) What are the high energy surface techniques used for surface hardening? Explain the electron beam hardening method.	5
7.	(a) Classify the conventional diffusion hardening processes according to the depth of hardening.	5
	(b) Explain the surface hardening methods used for alloy steel and stainless steel.	5
8.	Write short notes on any two: 5 ×	2
1	Electro-less plating	
	(ii) Thermal evaporation	
	(iti) Carbo-nitriding	
	(iv) Galvanizing.	U
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B.Tech - 7th(M & M)/Surface Engineering(Set-T₁)